

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	2153	(257/678).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/03/06 18:15
S2	1981	(257/787).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/03/01 12:12
S3	446	S2 and substrate and (chip IC integrated adj circuit die) and electrode	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 12:35
S4	506	S1 and substrate and (chip IC integrated adj circuit die) and electrode	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 13:32
S5	1	("20050116324").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/03/01 13:33
S6	27236	(257/6\$\$).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/03/01 13:33
S7	38967	(257/7\$\$).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/03/01 13:34
S8	4464	S6 and (mounting substrate) and (groove trench)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/03 12:22
S10	375	S7 and (mounting substrate) and (groove trench) and electrode and (encapsulat\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 13:35
S11	290	S6 and (mounting substrate) and (groove trench) and electrode and (encapsulat\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 14:29

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S12	4370	(mounting substrate) and (groove trench) and electrode and (encapsulat\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 14:29
S13	2974	(mounting substrate) and (groove trench) and electrode and (encapsulat\$3) and (die chip IC integrated adj circuit)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 14:29
S14	2417	S6 and (mounting substrate) and (groove trench) and electrode	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 14:30
S15	3383	S7 and (mounting substrate) and (groove trench) and electrode	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 14:31
S16	4969	(S14 S15) and (mounting substrate) and (groove trench) and electrode	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 14:31
S17	2455	(S14 S15) and (mounting substrate) and (groove trench) and electrode and (encapsulat\$3 passivat\$3 epoxy adhesive tape)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 15:19
S18	1605	(S14 S15) and ((mounting substrate) same (groove trench)) and electrode and (encapsulat\$3 passivat\$3 epoxy adhesive tape)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 15:29
S19	961	(S14 S15) and ((mounting substrate) same (groove trench)) and (electrode not (gate adj electrode)) and (encapsulat\$3 passivat\$3 epoxy adhesive tape)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 18:37

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S20	1	("6566747").PN.	US-PGPUB; USPAT; USOCR; JPO	OR	OFF	2006/03/01 16:16
S21	302	(S14 S15) and ((mounting substrate) same (groove trench)) and ((pad with metal) electrode not (gate adj electrode)) and ((encapsulat\$3 passivat\$3 epoxy adhesive tape) with (groove trench))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 18:40
S22	1	("6495914").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/03/03 12:07
S23	524	(257/620).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/03/03 12:13
S24	27285	(257/6\$\$).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/03/03 12:25
S25	39046	(257/7\$\$).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/03/03 12:25
S26	218	(S24 S25) and (substrate same (groove trench)) and (electrode) and (chip die IC integrated adj circuit) and encapsulat\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/03 16:08
S27	1	("6784544").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/03/03 16:06
S28	1	("20010042902").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/03/03 16:06
S30	5	(S24 S25) and (mount same substrate same (groove trench)) and (electrode) and (chip die IC integrated adj circuit) and encapsulat\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/03 16:11
S31	218	(S24 S25) and (substrate same (groove trench)) and (electrode) and (chip die IC integrated adj circuit) and encapsulat\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/03 16:32

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S32	32	(S24 S25) and (substrate same (groove trench) same encapsulat\$3) and (electrode) and (chip die IC integrated adj circuit)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/03 16:36
S33	39046	(257/7\$\$.CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/03/06 11:23
S36	1040	S33 and (mount substrate) and (groove trench)and (encapsul\$5) and (chip die integrated adj circuit IC)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/06 17:12
S37	1	("5688716").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/03/06 13:31
S38	323	S33 and (mount substrate) and (groove trench)and (encapsul\$5) and (chip die integrated adj circuit IC) and electrode	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/06 13:49
S39	1	("6303470").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/03/06 14:41
S40	1	("20040104473").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/03/06 14:41
S41	1	("2002244862").PN.	JPO	OR	OFF	2006/03/06 15:54
S42	1466	(mount substrate) and (groove trench)same(encapsul\$5) and (chip die integrated adj circuit IC)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/06 16:21
S43	512	(mount substrate) and (groove trench) same (encapsul\$5) and (chip die integrated adj circuit IC) and electrode	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/06 16:55
S44	1984	(257/787).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/03/06 16:55



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S45	63	S44 and (trench)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/06 16:55
S46	1	("6909178").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/03/06 18:01
S47	1	("5434745").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/03/06 18:01
S48	9	((("6909178") or ("6621161") or ("6548895") or ("20030075797") or ("20040227250") or ("20050045378") or ("20020113325") or ("20020011676") or ("6979895")). PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/03/06 18:17
S49	1	"6020629".PN.	USPAT; USOCR	OR	ON	2006/03/07 09:53
S50	1	("6909178").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/03/07 09:55
S51	1	S50 and (electrode) and (groove trench recess) and (encapsula\$4) and substrate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/07 10:14
S52	1	"6621161" and trench and electrode and encapsula\$4 and substrate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/07 10:15